

Polishing Pads

Polishing pads are classified as either non-woven and woven. Woven polishing pads are fiber woven textile cloths, whereas, non-woven pads are polymeric pads which typically have a porous structure.

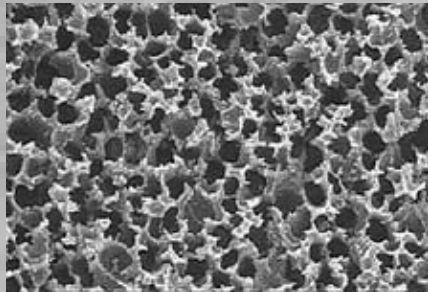
PACE Technologies offers a wide selection of woven and non-woven polishing pads for industrial polishing operations. Our woven products include our low napped DACRON and POLYPAD pads, as well as our high napped MICROPAD.

The non-woven products include our PC urethane impregnated

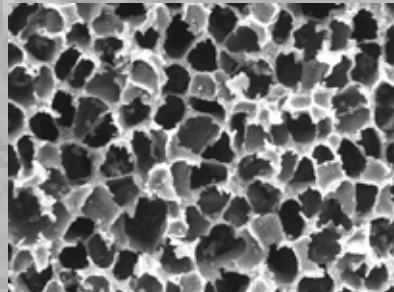
polishing pads as well as our more chemically resistant BLACKCHEM 2 polishing pad.

Our polishing pads offer an affordable alternative to competitive products from company's such as RODEL.

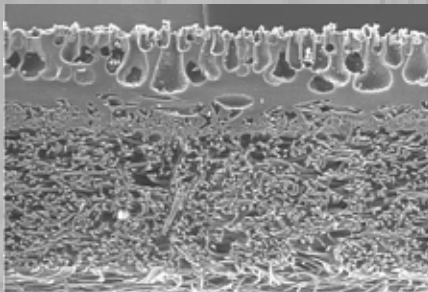
BLACKCHEM 2 is a replacement polishing pad for the POLITEX polishing pad (see comparison table below). Its main application is for CMP polishing with alumina or colloidal silica. The BLACKCHEM 2 also has a very similar and porous structure as the POLITEX pad.



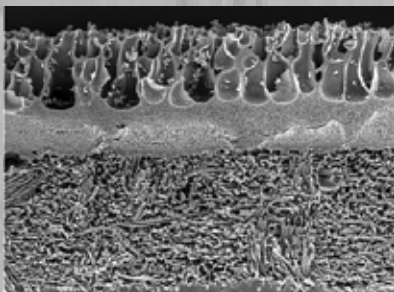
Pore Structure BLACKCHEM 2 (SEM 300X)



Pore Structure POLITEX (SEM 300X)



Cross Section for BLACKCHEM 2 (SEM 100X)



Cross Section for POLITEX (SEM 100X)

Properties	PACE Blackchem 2	RODEL POLITEX
Thickness in mm (DIN 53353)	1.369	1.471
Weight g/m ² (DIN 53353)	583.1	582.6
Hardness, Shore A (DIN 53505)	66	61
Compressibility in %		
-after 100 s weight	67.8	62.9
-after 100 s relief	94.33	96.8
Surface resistance in mg	1.3	n.a.
-5000 friction cycles mass loss / 100 turns		
% Open pore volume	68.6	78.1
Average pore size in microns	40.6	55
Wetting angle (water)		
-start	80 degrees	134 degrees
-after 10 s	no water	142 degrees
-after 600 s	no water	132 degrees



PACE TECHNOLOGIES

POLISHING PADS

**-Semiconductor Wafers
-Optical Components
-Magnetic Wafers**

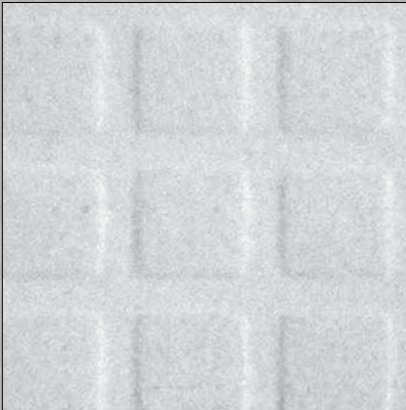


Impregnated Felt Polishing Pads

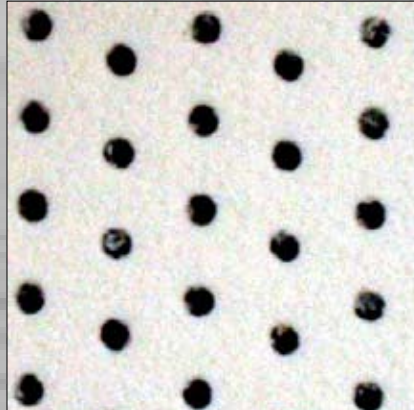
The PC series of polishing pads are urethane impregnated polishing pads. They are alternative polishing pads for the

SUBA series of polishing pads (see following comparison table). The main polishing applications for these pads are for glass, ceramics, precision optics and other materials where surface finish is critical.

PACE	Replaces	Specific Gravity	Durometer Hardness	Thickness	Max size
PC80	SUBA 500	0.58	<C80	0.050" - 1"	39.5" x 39.5"
PC60	SUBA V	040	>C60	0.005" - 1"	39.5" x 39.5"
PC40	SUBA IV / GS	0.34	C40 B60	0.90" - 1"	53" x 53"
PC55-LD	SUBA X	0.32	C55 B75	0.050" - 1"	39.5" x 39.5"
PC55-HD	SUBA X	0.42	C55 B75	0.050" - 1"	39.5" x 39.5"
PC20	Natural wool	0.31	C20 B75	1/8" - 1"	53" x 53"



PC60 Embossed Polishing Pad

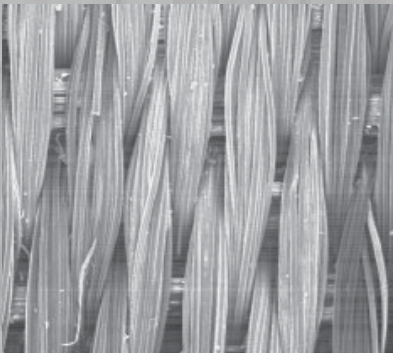


PC60 Perforated Polishing Pad

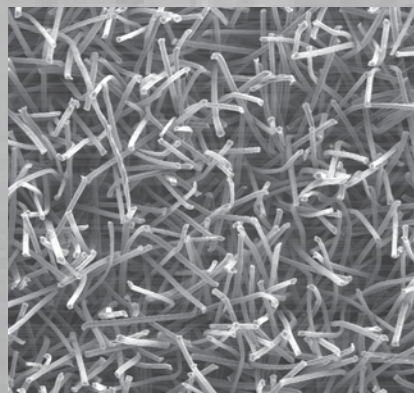
Woven Polishing Pads

The DACRON and POLYPAD polishing pads have a low napped woven polishing design as shown below. These pads are very durable and are excellent polishing pads for intermediate sized diamond, silicon carbide, ceria, or alumina polishing slurries.

The MICROPAD final polishing pad is a high napped or flocked polishing pad. It produces a relatively gentle polishing action and is very useful for polishing metals and other soft materials.



DACRON woven polishing pad



MICROPAD high napped polishing pad



PACE TECHNOLOGIES

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